



SOT994-1

plastic thermal enhanced very very thin quad flat package;
no leads; 24 terminals; 0.5 mm pitch, 4 mm x 4 mm x 0.75 mm
body

26 September 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HWQFN24
Package type industry code	HWQFN24
Package style descriptive code	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	20-09-2019
Manufacturer package code	SOT994

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.9	4	4.1	mm
package width	3.9	4	4.1	mm
seated height	-	0.75	0.8	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	24	-	



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2 Package outline

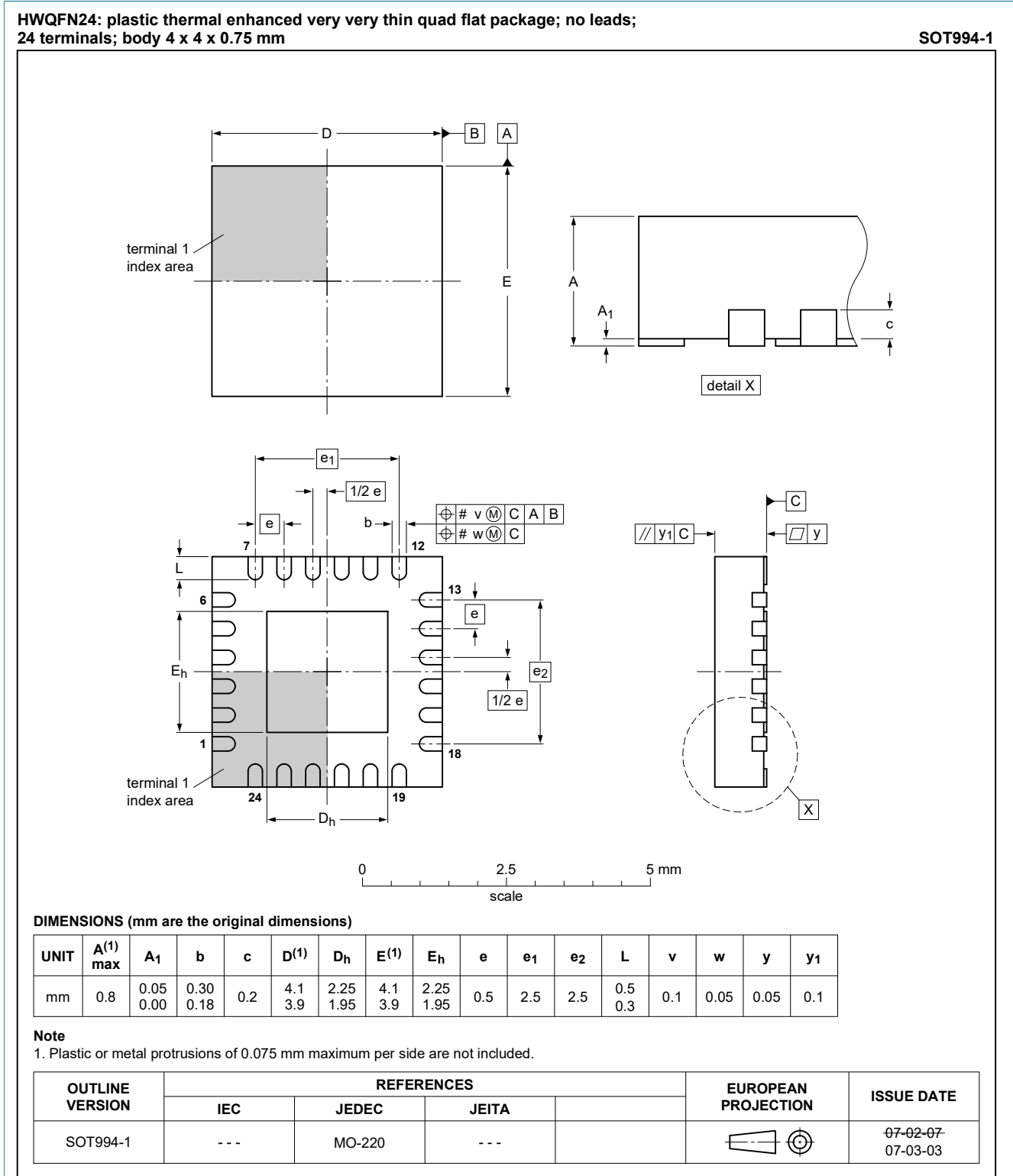
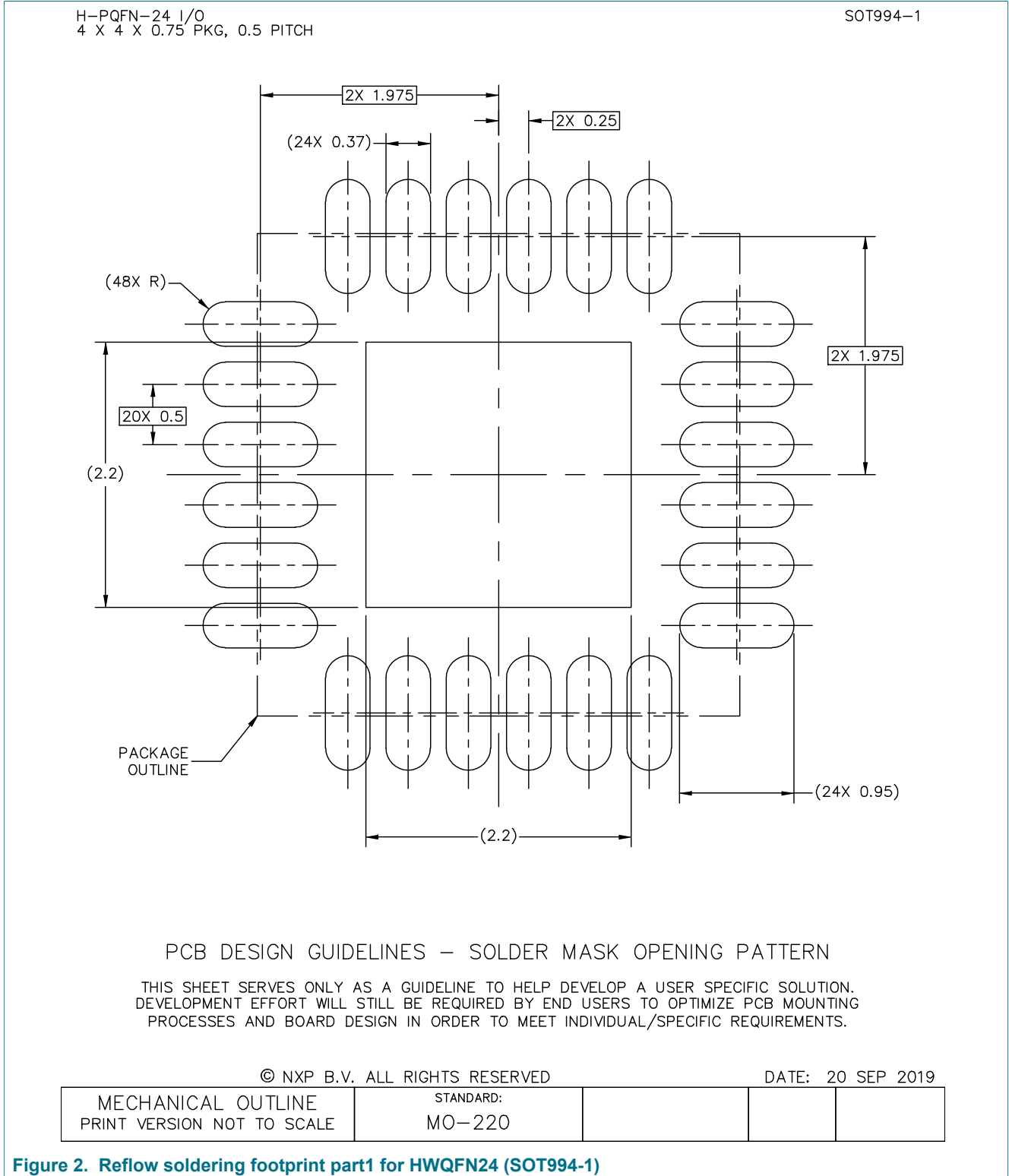


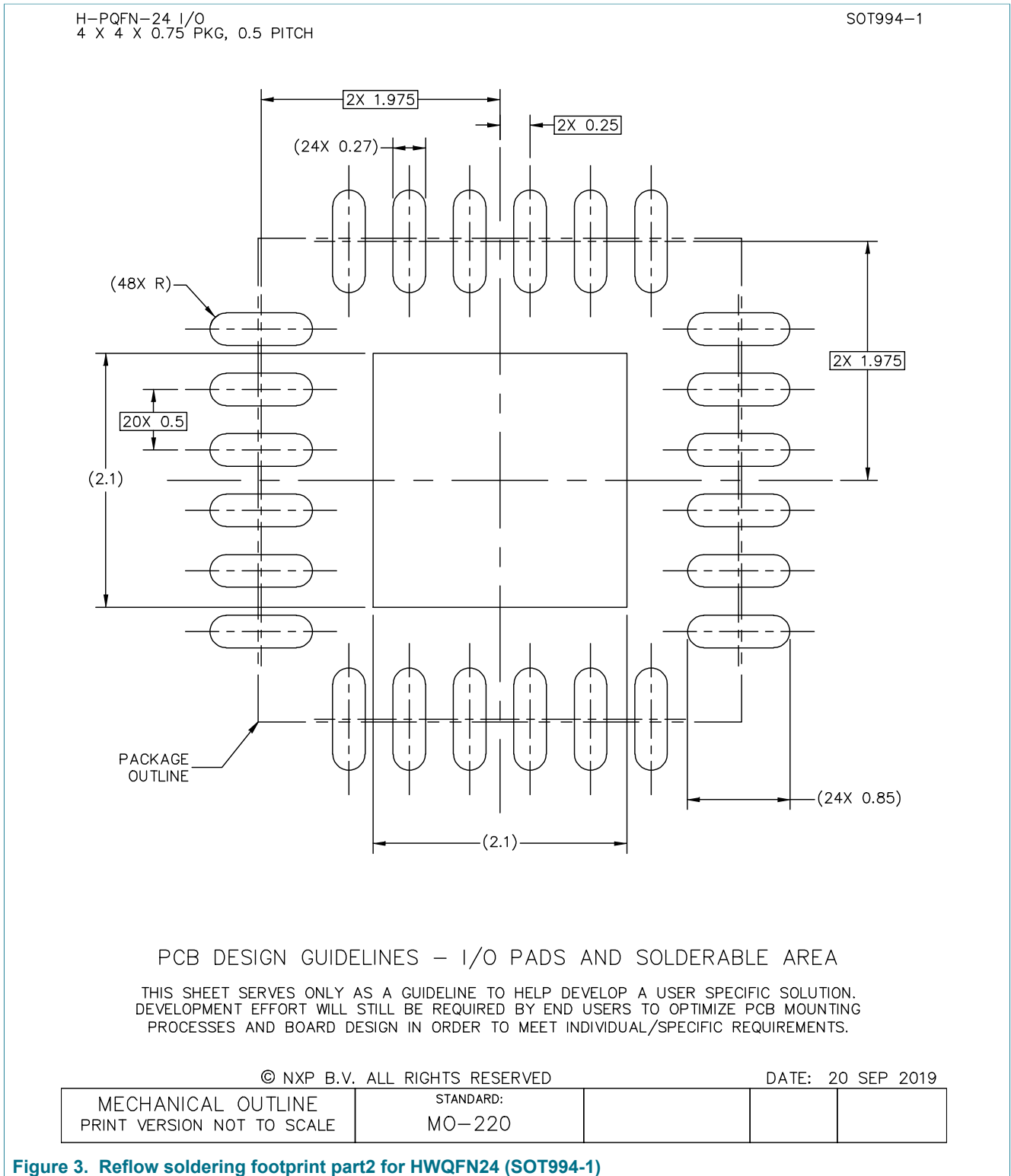
Figure 1. Package outline HWQFN24 (SOT994-1)

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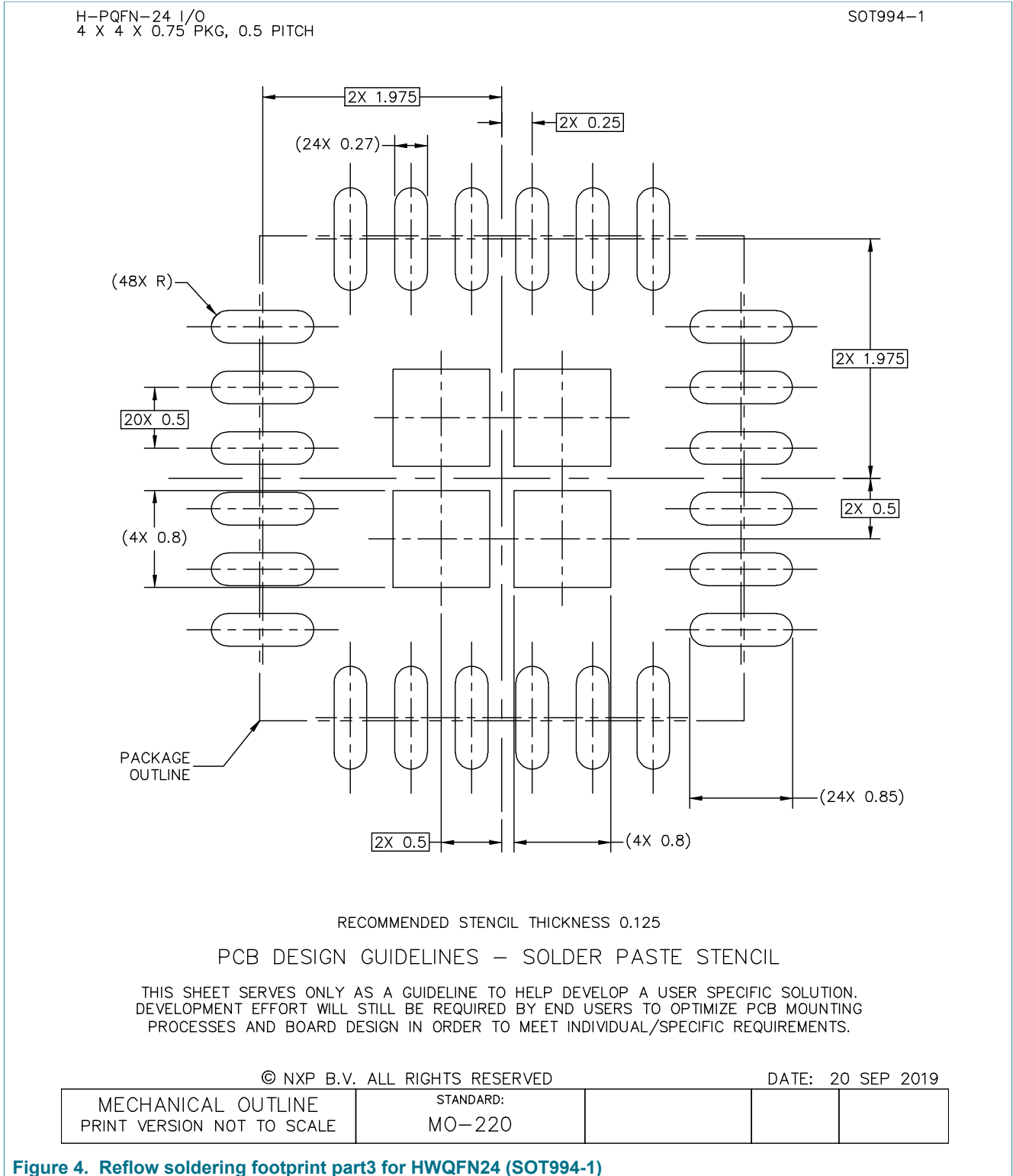
3 Soldering



plastic thermal enhanced very very thin quad flat package; no leads; 24 terminals; 0.5 mm pitch, 4 mm x 4 mm x 0.75 mm body



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4 Legal information

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